

ABSTRACT

A laminated flip-chip interconnect package comprising a substrate having a chip attach surface and a board attach surface that define contact pads for attachment to corresponding pads on the chip and board wherein the substrate board surface comprises at least one solid plane covering the chip attach surface region near at least one chip corner. In one embodiment, the solid plane comprises a dielectric material, optionally covered with a soldermask or coverlay material. In an alternate embodiment, the solid plane comprises a metal, optionally covered with a soldermask or coverlay material.